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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Attorney Docket Number	245-66956-01
Application Number	10/683,575
Filing Date	October 9, 2003
First Named Inventor	Ozis
Art Unit	~~2123~~ 2128
Examiner Name	Frejd

Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS
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RF		Özişş, Dicle "An Efficient Modeling Approach for Substrate Noise Coupling Analysis with Multiple Contacts in Heavily Doped CMOS Processes," Masters Thesis, Oregon State University, OR, 93 pp. (2002).
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RF		Su et al., "Experimental Results and Modeling Techniques for Substrate Noise in Mixed-Signal Integrated Circuits," *IEEE Journal of Solid-State Circuits*, Vol. 28, No. 4, pp. 420-430 (April 1993).
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EXAMINER SIGNATURE:	/Russell Frejd/	DATE CONSIDERED:	05/23/2006

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